



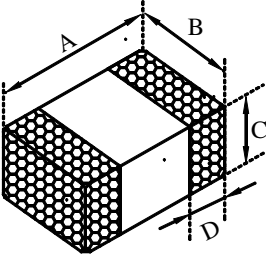
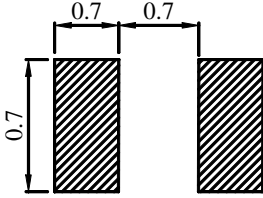
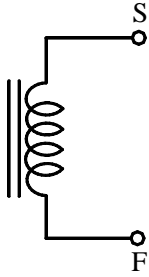


剛松股份有限公司  
GANG SONG ELECTRONICS CO., LTD.  
SPECIFICATION FOR APPROVAL

1.0

CUST. NAME		(Q014)		DATE			
DESCRIPTION		Multilayer Chip Beads		TYPE			
GS PART NO.		GSMB160808 – U0330		DWG. NO.			
CUST. PART NO.				GS SAMPLE NO.			
DIM	Unit in mm	MECHANICAL MEASUREMENTS					
A	1.6±0.2					  	
B	0.8±0.2						
C	0.8±0.2						
D	0.2~0.6						
E							
F							
G							
H							
I							
J							
K							
L							
M							
N							
ELECTRICAL MEASUREMENTS & TEST EQUIPMENT					Remark :		
NO.	Z (Ω) @100MHz/ 500mV	Q (min) @	SRF(min) MHz	DCR(max) (Ω)	IDC(max) (mA)		
EQU.	HP4291A			HP4338A	WK3260B		
SPE.	330±25%			0.30	400		
1							
2							
3							
4							
5							
6							
7							
8							
9							
10							
DRAWN BY: Mavis		CHECKED BY: Ching Chung		APPROVED BY: William			

剛松股份有限公司  
GANG SONG ELECTRONICS CO., LTD.  
SPECIFICATION FOR APPROVAL

1.0

2/2

CUST. NAME	(Q014)	DATE	
DESCRIPTION	Multilayer Chip Beads	TYPE	
GS PART NO.	GSMB160808 – U0330	DWG. NO.	
CUST. PART NO.		GS SAMPLE NO.	

